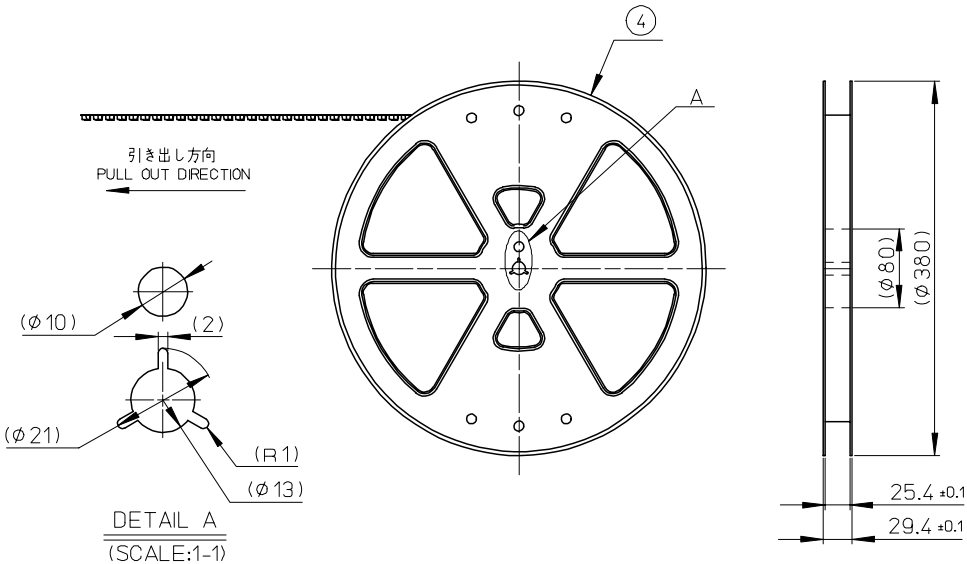


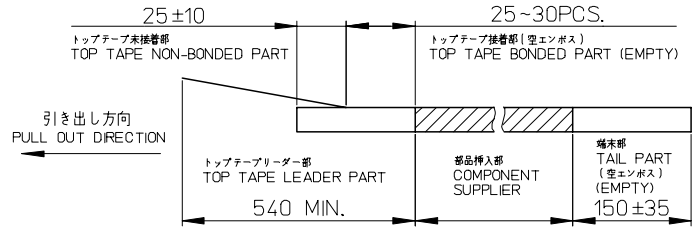
10 9 8 7 6 5 4 3 2 1

①	コネクタ CONNECTOR
②	エンボステープ EMBOSSSED TAPE
③	トップテープ TOP TAPE
④	リール REEL

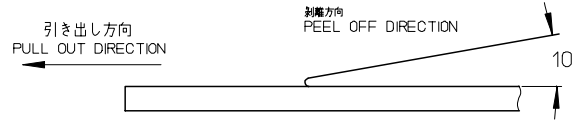


注記

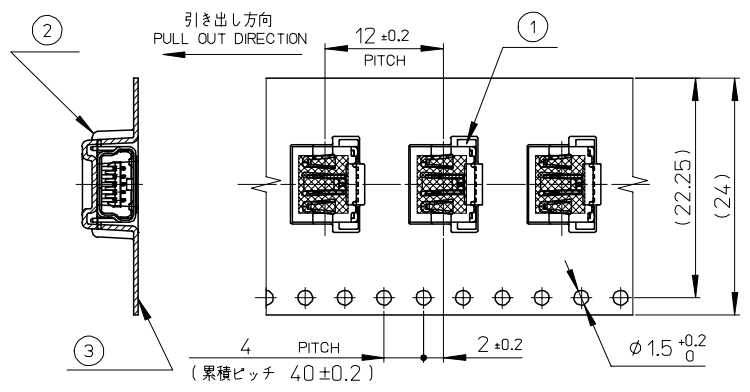
- コネクタ詳細は SD-51387-006を参照下さい。  
REFER TO SD-51387-006
- 梱包数量: 1200個/リール  
NUMBER OF CONNECTOR : 1200 PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- トップテープの剥離強度:  $0.6 \pm 0.35N$  ( $60 \pm 35gf$ )  
<剥離速度: 300mm/min (参考)> (剥離方向は下図参照)  
PEEL-OFF FORCE OF TOP TAPE :  $0.6 \pm 0.35N$  ( $60 \pm 35gf$ )  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
<PEEL-OFF SPEED : 300mm/min (REF.)>



- 材料  
MATERIAL  
キャリアテープ: ポリプロピレン  
CARRIER TAPE : POLYPROPYLENE  
トップテープ : ポリエステル, ポリエチレン  
TOP TAPE : POLYESTER, POLYETHYLENE  
リール : ポリスチレン  
REEL : POLYSTYREN



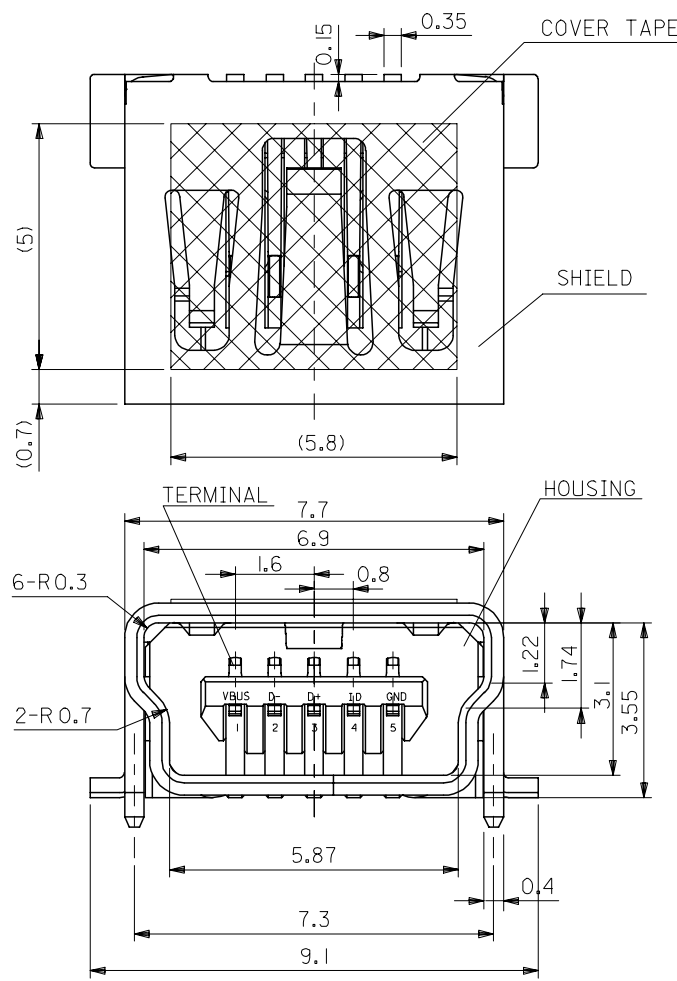
エンボステープ内の製品の向き  
DIRECTION OF PRODUCT  
IN EMBOSSSED TAPE  
(SCALE:2-1)

51387-0530	51387-***0
製品番号 MATERIAL No.	MODEL No.

新編作成 EC NO: J2005-0570 DRAWN: MSHINYAMA 2004/08/30 CHKD: HTAKASE 2004/08/30 APPR: JMIYAZAWA 2004/09/02 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MSHINYAMA	DATE 04/07/18	TITLE EMBOSSSED TAPE PKG. FOR 51387-0539 -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/07/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY JMIYAZAWA	DATE 04/07/18	DOCUMENT NO. SD-51387-005	SHEET NO. 1 OF 1	
	ANGULAR	±3 °	MATERIAL NO. SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

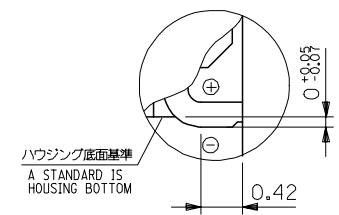
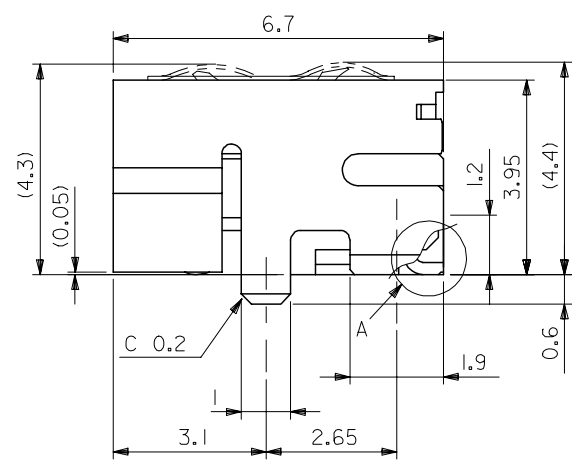
F  
E  
D  
C  
B  
A



注記  
NOTES

1. 材質  
MATERIAL  
ハウジング:耐熱樹脂 ガラス充填, 黒色, UL94V-0  
HOUSING:HEAT RESISTANT PLASTIC,  
GLASS FILLED,BLACK,UL94V-0  
ターミナル:銅合金 (t=0.25)  
TERMINAL:COPPER ALLOY(t=0.25)  
シールド:銅合金 (t=0.4)  
SHIELD :COPPER ALLOY(t=0.4)  
カバー テープ:ポリイミド (t=0.08)  
COVER TAPE:POLYIMIDE (t=0.08)

2. メッキ仕様  
PLATING  
ターミナル 接点部:金メッキ  
TERMINAL CONTACT AREA:GOLD  
半田付け部:錫メッキ  
SOLDER TAIL AREA:TIN  
下地部:ニッケルメッキ  
UNDER PLATING:NICKEL  
シールド:錫メッキ  
SHIELD :TIN  
下地部:ニッケル  
UNDER PLATING:NICKEL  
3. 平坦度は0.1mm MAX.  
COPLANARITY 0.1mm MAX.



DETAIL A  
(SCALE 20:1)

5	51387-0539
極数 CKT.	製品番号 MATERIAL NO.

REVISED EC NO: J2007-2931 DRWN: AYOYAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APP: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/06/18				
	30 OVER	±0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-51387-006		1 OF 2		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

10 9 8 7 6 5 4 3 2 1

F

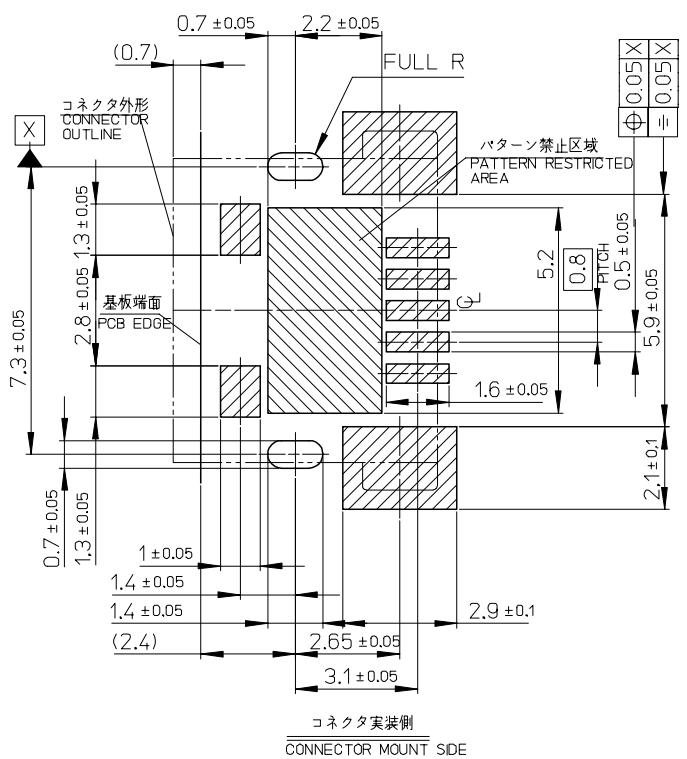
E

D

C

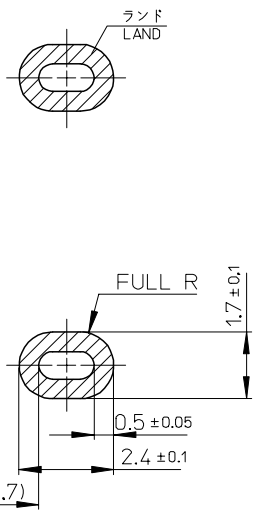
B

A

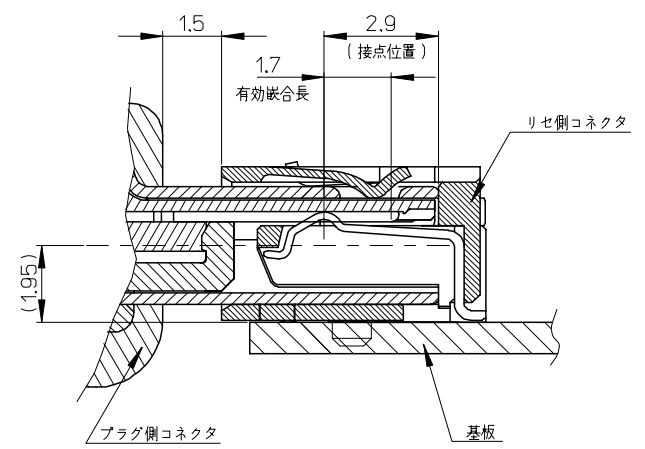


コネクタ実装側  
CONNECTOR MOUNT SIDE

推奨基板寸法 (SCALE 8:1)  
RECOMMENDED PCB PATTERN LAYOUT



逆側  
REVERSE SIDE



コネクタ嵌合図  
(SCALE 8:1)

REVISED EC NO: J2007-2931 DRWN: A0YAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APPR: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY MSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE-	
	10 OVER 30 UNDER	± 0.25	CHECKED BY HTAKASE	DATE 04/06/18	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	DOCUMENT NO. SD-51387-006	SHEET NO. 2 OF 2
	ANGULAR	± 3 °	MATERIAL NO. SEE SHEET 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				